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**Amendments to the claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of claims:**

Claim 1 (currently amended): A ground-enhanced semiconductor package, comprising:

a lead frame having at least one die pad, a plurality of tie bars connected with and supporting the die pad, a plurality of leads surrounding the die pad, and a ~~ground structure~~plurality of ground structures surrounding the die pad;

wherein the ground ~~structure~~structures are separated from each other and each of the ground structures comprises at least one of first ground portions directly connected to the tie bars so as to prevent deformation of the ground structure to assure grounding performance of the semiconductor package, wherein the first ground portions are separate from each other and are connected to both lateral sides of the tie bars, and a hollow-out area is formed between the first ground ~~portion and one of the tie bars~~portions;

at least one chip mounted on the die pad and electrically connected to the leads and the first ground portion of the ground structure by bonding wires; and

an encapsulation body for encapsulating the chip and the lead frame.

Claim 2 (previously presented): The ground-enhanced semiconductor package of claim 1, further comprising at least one of second ground portions connected to the die pad, wherein the second ground portions are separate from each other and from the first ground portions.

Claim 3 (original): The ground-enhanced semiconductor package of claim 1, wherein the first ground portion is connected to the die pad.

Claim 4 (previously presented): The ground-enhanced semiconductor package of claim 3, wherein the first ground portion comprises a ground area and a connection area which are interconnected to form the hollow-out area together with one of the tie bars.

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Claim 5 (original): The ground-enhanced semiconductor package of claim 1, wherein the first ground portion is not connected to the die pad.

Claim 6 (original): The ground-enhanced semiconductor package of claim 5, wherein the first ground portion is shaped as a strip.

Claim 7 (previously presented): The ground-enhanced semiconductor package of claim 2, wherein the second ground portion comprises a ground area and at least one connection area which are interconnected to form a hollow-out area together with a side edge of the die pad.

Claim 8 (original): The ground-enhanced semiconductor package of claim 1, wherein each of the tie bars is formed with at least one of the first ground portions.

Claim 9 (canceled)

Claim 10 (previously presented): The ground-enhanced semiconductor package of claim 2, wherein each side edge of the die pad is formed with at least one of the second ground portions.

Claim 11 (currently amended): A lead frame for a semiconductor package, comprising:

a body having at least one die pad, a plurality of tie bars connected with and supporting the die pad, and a plurality of leads surrounding the die pad; and

a ground structure comprising a plurality of ground structures surrounding the die pad, wherein the ground structures are separated from each other and each of the ground structures comprises at least one of first ground portions directly connected to the tie bars so as to prevent deformation of the ground structure to assure grounding performance of the semiconductor package, wherein the first ground portions are separate from each other and are connected to both lateral sides of the tie bars, and a hollow-out area is formed between the first ground portion and one of the tie bars portions.

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Claim 12 (previously presented): The lead frame of claim 11, further comprising at least one of second ground portions connected to the die pad, wherein the second ground portions are separate from each other and from the first ground portions.

Claim 13 (original): The lead frame of claim 11, wherein the first ground portion is connected to the die pad.

Claim 14 (previously presented): The lead frame of claim 13, wherein the first ground portion comprises a ground area and a connection area which are interconnected to form the hollow-out area together with one of the tie bars.

Claim 15 (original): The lead frame of claim 11, wherein the first ground portion is not connected to the die pad.

Claim 16 (original): The lead frame of claim 15, wherein the first ground portion is shaped as a strip.

Claim 17 (previously presented): The lead frame of claim 12, wherein the second ground portion comprises a ground area and at least one connection area which are interconnected to form a hollow-out area together with a side edge of the die pad.

Claim 18 (original): The lead frame of claim 11, wherein each of the tie bars is formed with at least one of the first ground portions.

Claim 19 (canceled)

Claim 20 (previously presented): The lead frame of claim 12, wherein each side edge of the die pad is formed with at least one of the second ground portions.